

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10750059
<b>Filing Date:</b>	30-Dec-2003
<b>Title of Invention:</b>	SOLDER BALL PAD STRUCTURE

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Filer:	Yingsheng Tung/Jackie McBride
Attorney Docket Number:	TI-36833

Filed as Large Entity

<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)

**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Utility Appl Issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1740</b>